

## **NOTIFICATION OF REASONS FOR REJECTION**

Patent Application No.: Patent Application No. 2002-312456

Drafting Date: June 19, 2008

JPO Examiner: Hiroshi Okazawa 3320 3U00

Agent of Patent Applicant: Mr. Kenzo Matsuura

Applied Provision: Patent Law, Articles 29(1) and 29(2)

The present application should be rejected for the reasons mentioned below.

Arguments against the reasons, if any, should be submitted in writing within sixty days from the dispatch date of this notification.

### **Reasons**

1. The inventions described in the claims mentioned below of the present application should not be granted a patent under Article 29(1), (iii) of the Patent Law since they are described in the publications mentioned below which were distributed in Japan or foreign countries prior to the filing of the present application, or were made available to the general public through telecommunication lines in Japan or foreign countries prior to the filing of the present application.
2. The inventions described in the claims mentioned below of the present application should not be granted a patent under Article 29(2) of the Patent Law since they could have been easily made, prior to the filing of the present application, by those who have common knowledge in the technical field to which said inventions pertain, on the basis of the inventions described in the publications mentioned below which were distributed in Japan or foreign countries prior to the filing of the present application or on the basis of the inventions made available to the general public through telecommunication lines in Japan or foreign countries prior to the filing of the present application.

Note (for cited documents etc., see the list of cited documents etc.)

- Reasons: 1, 2
- Claims: 1 to 5
- Cited document, etc.: 1
- Remark:

The cited document 1 describes a step of conveying a wafer with increased spacings between chips being maintained.

With respect to Claim 4, in particular, the art of heating and expanding a sheet is well-known (see, for example, the cited document 2 and Japanese Patent Application Laid-Open No. 4-255243).

- Reasons: 1, 2
- Claims: 1 to 4
- Cited document, etc.: 2
- Remark:

The cited document 2 describes a step of conveying a wafer with increased spacings between chips being maintained.

List of cited documents etc.

1. Japanese Patent Application Laid-Open No. 2001-102329
2. Microfilm of Japanese Utility Model Application No. 51-37226 (Laid-Open Japanese Utility Model Publication No. 52-127762)

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Record of the results of prior art search

- Technical fields searched: IPC H01L 21/78

This record is not a component of the reason for rejection.

For any inquiries about this notification or any requests for interviews about the present application, contact Hiroshi Okazawa, Robotics, Production Machinery Division, 2nd Patent Examination Department at 03-3581-1101 (extension 3324).